

wherein said terminal portion further includes a base layer, and a conductive layer disposed between said base layer and said nickel plating layer, wherein a thickness of said base layer comprises polyimide resin,

wherein said soldering bump contains tin and at least one of silver and copper.

Claim 2 (Canceled).

3. (Original) A circuit board according to Claim 1, wherein said soldering bump contains tin, silver and copper.

4. (Previously Amended) A circuit board according to Claim 1, wherein said circuit board is a circuit provided suspension substrate.

5. (Currently Amended) A connection structure for connecting a terminal portion of a circuit board with an external terminal formed in an external circuit, wherein said terminal portion is provided with a nickel plating layer and a soldering bump provided on said terminal portion and a thickness of said nickel plating layer is within a range of 1.0 to 4.0 μm , and

wherein said terminal portion is further provided with a base layer and a conductive layer, which is disposed between said base layer and said nickel plating layer, and wherein said base layer comprises [poyimide] polyimide resin.

AMENDMENT UNDER 37 C.F.R. § 1.116
U.S. Appln. No. 09/974,048

6. (Previously Added) The circuit board according to claim 1, wherein a thickness of the base layer is 2-30 μm .

7. (Previously Added) The circuit board according to claim 1, wherein a thickness of the conductive layer is 3-25 μm .

8. (Previously Added) The circuit board according to claim 1, wherein the terminal portion further includes a cover layer disposed on said base layer, having a thickness of .5 - 8.0 μm .

9. (Previously Added) The circuit board according to claim 3, wherein a composition ratio of said soldering bump is 95-97% by weight of said tin, 0-4% by weight of said silver, and 0-4% by weight of said copper.